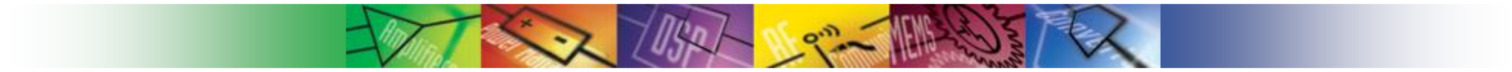

Product / Package Information

Package	LFCSP
Body Size (mm)	2 X 2 X 0.85 (1 X 1.6 EP)
Lead Count	6
Terminal Finish	NiPdAu
MS Number	MS012249C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	05-Sep-19

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.22E-03	84.50	845000	42.21	422141
Thermosets	Epoxy & Phenol resin	Proprietary	5.72E-04	15.00	150000	7.49	74936
Other inorganic materials	Carbon black	1333-86-4	1.91E-05	0.50	5000	0.25	2498
Subtotal			3.81E-03	100.00	1000000	49.96	499575

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.38 E-03	97.50	975000	44.32	443241
Copper & its alloys	Iron	7439-89-6	8.15 E-05	2.35	23500	1.07	10683
Copper & its alloys	Zinc	7440-66-6	4.16 E-06	0.12	1200	0.05	546
Copper & its alloys	Phosphorus	7723-14-0	1.04 E-06	0.03	300	0.01	136
Subtotal			3.47 E-03	100.00	1000000	45.46	454606

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	1.89 E-04	95.02	950185	2.48	24754
Precious metals	Palladium	7440-05-3	8.07 E-06	4.06	40590	0.11	1057
Precious metals	Gold	7440-57-5	1.83 E-06	0.92	9225	0.024	240
Subtotal			1.99 E-04	100.00	1000000	2.61	26052

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.49 E-05	99.00	990000	0.59	5883
Precious metals	Palladium	7440-05-3	4.53 E-07	1.00	10000	0.006	59
Subtotal			4.53 E-05	100.0	1000000	0.59	5942

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	5.49 E-05	100.0	1000000	0.72	7193

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.90 E-05	77.00	770000	0.51	5106
Other organic materials	Acrylic resin	Proprietary	3.54 E-06	7.00	70000	0.05	464
Other organic materials	Acrylate	Proprietary	2.78 E-06	5.50	55000	0.04	365
Other organic materials	Polybutadiene derivative	Proprietary	2.28 E-06	4.50	45000	0.03	298
Thermoset	Epoxy resin	Proprietary	1.26 E-06	2.50	25000	0.02	166
Other organic materials	Butadiene Copolymer	Proprietary	7.59 E-07	1.50	15000	0.01	99
Others	Additive	Proprietary	7.59 E-07	1.50	15000	0.01	99
Others	Peroxide	Proprietary	2.53 E-07	0.50	5000	0.003	33
Subtotal			5.06 E-05	100.0	1000000	0.66	6631

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.63 E-03**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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